RC5032 5V to 3.3V Step-Down DC-DC Converter

Features

- >85% Efficiency
- Fast transient response
- Soft control power-up
- · Short circuit protection
- Output voltage fixed 3.3V

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- Low TC reference voltage
- Adjustable oscillator frequency
- Drives N-Channel MOSFET
- 8 pin SOIC, 8 pin DIP package

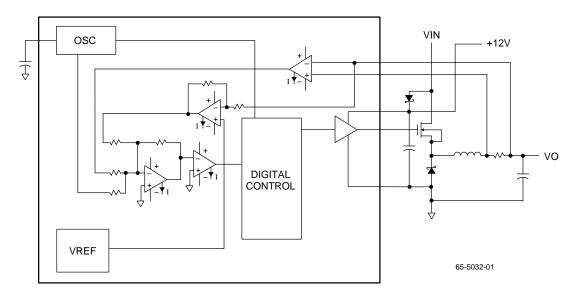
Applications

- 3.3V power supply for Pentium[™] based desktop CPU motherboards
- Minimum component DC-DC converters

Description

The RC5032 is a step-down DC-DC controller IC dedicated to providing a 5V to 3.3V conversion for various types of CPU power. It can be configured with the proper applications circuitry to deliver load currents greater than 10 Amps. The RC5032 is designed to operate in a standard PWM control mode under heavy load conditions and as a PFM controller in light load conditions. Its highly accurate low TC reference eliminates the need for precision external components in order to achieve tight tolerance voltage regulation.

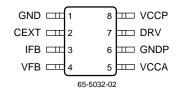
The programmable oscillator can operate from 200KHz to greater than 1MHz to provide for flexibility in choosing external components such as inductors, capacitors, and Power MOSFETs.



Block Diagram

PRELIMINARY INFORMATION describes products that are not in full production at the time of printing. Specifications are based on design goals and limited characterization. They may change without notice. Contact Fairchild Semiconductor for current information.

Pin Assignments



Pin Definitions

Pin Name	Pin Number	Pin Function Description		
GND	1	Ground		
CEXT	2	External capacitor for setting oscillator frequency		
IFB	3	Current Feedback Input		
VFB	4	Voltage Feedback Input		
VCCA	5	Analog VCC		
GNDP	6	Power ground for high current driver		
DRV	7	FET Driver Output		
VCCP	8	VCC for FET output drivers		

Absolute Maximum Ratings

(beyond which the device may be damaged)¹

Paramete	er	Conditions	Min	Тур	Max	Units
VCCP	Driver Supply				13	V

Note:

1. Functional operation under any of these conditions is NOT implied. Performance is guaranteed only if Operating Conditions are not exceeded.

Operating Conditions

Parameter		Conditions	Min	Тур	Max	Units
VCC	Supply Voltage		4.5	5	7	V
VCCP	Driver Supply		9		13	V
VIH	Input Voltage, Logic HIGH		2			V
VIL	Input Voltage, Logic LOW				0.8	V
	Ambient Temp		0		70	°C

DC Electrical Characteristics

(V_{CC} = 5V, Fosc = 650 KHz, and T_A = 0–70 $^{\circ}$ C)

Parameter		Conditions	Min	Тур	Max	Units
Vo	Output Voltage		3.1	3.4	3.6	V
lo	Output Current	See Figure 1 for application		7		A
Vref Acc	Reference Accuracy			1	3	%
VTC	Output Voltage TC			40		ppm
LDR	Load Regulation	0.5 to 7A		0.5		%Vo
LIR	Line Regulation	V _{CC} = ±5%		0.07		%Vo
VR	Output Voltage Ripple			30		mV
Cum Acc	Cumulative Accuracy ¹	$T_{A} = 0 - 70^{\circ}C$		3	5	%
Eff	Efficiency	lload > 4A	85	88		%
lodr	Output Driver I	Open Loop	0.5	0.7		A
Pd	Power Dissipation			0.1		W

Notes:

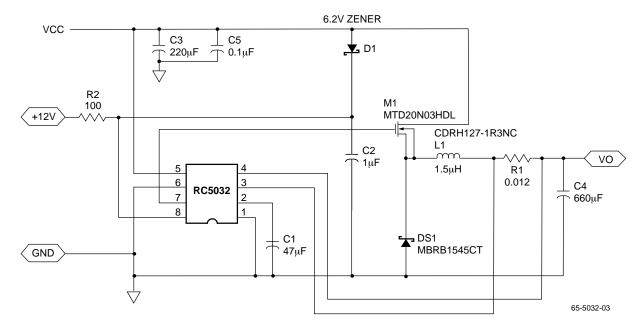
1. Output Voltage accuracy, Tempco, load regulation, ripple, and transient performance determine the Cumulative Accuracy.

AC Electrical Characteristics

(V_{CC} = 5V, Fosc = 650 KHz, and T_A = 25° C)

Parameter		Conditions	Min	Тур	Max	Units
Tr	Response Time	II=0.5A to 7A		10		μs
Fosc	Oscillator Range		0.2		1.2	MHz
Osc Acc	Fosc Accuracy			10		%
Dtc	Max Duty Cycle	PWM mode	90	95		%
Dtcm	Min Duty Cycle	PFM mode			100	ns
Iscp	Short Circuit Prot			250		mV
Trimax	Response to Imax			15	30	μs
Tssp	Soft start response			1		ms

Test Circuit



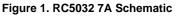


Table 1. Components for RC5032

	RC5032 Standard Application Circuit Bill of Materials					
Ref Designator	Quantity	Part No.	Manufacturer			
L1	1	CDRH127-1R3NC	Sumida			
M1	1	MTD20N03HDL	Motorola			
DS1	1	MBRB1545CT	Motorola			
D1	1	6.2V Zener	any			
R1	1	LRC-2512	IRC			
C3	1	OS-CON 10SA220M	Sanyo			
C4	2	OS-CON 10SA330M	Sanyo			
C2	1	1uF	Monolithic ceramic Cap			
C1	1	47pF	SMD Cap			
C5	1	0.1uF	SMD Cap			
R2	1	100Ω	SMD Res			

Notes:

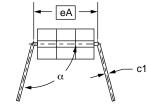
Mechanical Dimensions

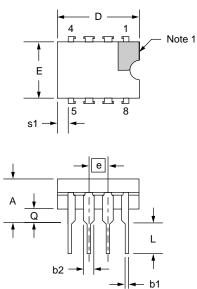
8 Lead Ceramic DIP Package

Symbol	Inc	Inches Millimeters		Millimeters	
Symbol	Min.	Max.	Min.	Max.	Notes
А	_	.200	_	5.08	
b1	.014	.023	.36	.58	8
b2	.045	.065	1.14	1.65	2, 8
c1	.008	.015	.20	.38	8
D	_	.405	_	10.29	4
Е	.220	.310	5.59	7.87	4
е	.100	BSC	2.54	BSC	5, 9
eA	.300	.300 BSC		BSC	7
L	.125	.200	3.18	5.08	
Q	.015	.060	.38	1.52	3
s1	.005	_	.13	_	6
α	90°	105°	90°	105°	

Notes:

- 1. Index area: a notch or a pin one identification mark shall be located adjacent to pin one. The manufacturer's identification shall not be used as pin one identification mark.
- 2. The minimum limit for dimension "b2" may be .023 (.58mm) for leads number 1, 4, 5 and 8 only.
- 3. Dimension "Q" shall be measured from the seating plane to the base plane.
- 4. This dimension allows for off-center lid, meniscus and glass overrun.
- The basic pin spacing is .100 (2.54mm) between centerlines. Each pin centerline shall be located within ±.010 (.25mm) of its exact longitudinal position relative to pins 1 and 8.
- 6. Applies to all four corners (leads number 1, 4, 5, and 8).
- 7. "eA" shall be measured at the center of the lead bends or at the centerline of the leads when " α " is 90°.
- 8. All leads Increase maximum limit by .003 (.08mm) measured at the center of the flat, when lead finish applied.
- 9. Six spaces.





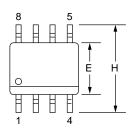
Mechanical Dimensions (continued)

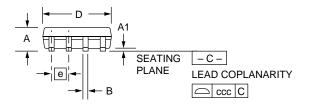
8 Lead SOIC Package

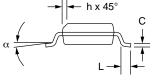
Symbol	Inc	hes	Millimeters		Notes
Symbol	Min.	Max.	Min.	Max.	Notes
А	.053	.069	1.35	1.75	
A1	.004	.010	0.10	0.25	
В	.013	.020	0.33	0.51	
С	.008	.010	0.20	0.25	5
D	.189	.197	4.80	5.00	2
Е	.150	.158	3.81	4.01	2
е	.050 BSC		1.27	BSC	
Н	.228	.244	5.79	6.20	
h	.010	.020	0.25	0.50	
L	.016	.050	0.40	1.27	3
Ν	8		5	3	6
α	0°	8°	0°	8°	
CCC		.004		0.10	

Notes:

- 1. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- 2. "D" and "E" do not include mold flash. Mold flash or protrusions shall not exceed .010 inch (0.25mm).
- 3. "L" is the length of terminal for soldering to a substrate.
- 4. Terminal numbers are shown for reference only.
- 5. "C" dimension does not include solder finish thickness.
- 6. Symbol "N" is the maximum number of terminals.







Ordering Information

Product Number	Package	θ JA
RC5032M	8 SOIC	85°C/W

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